

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon Carbide (SiC)	409-21-2	0.02	100.0	1
			Subtotal	0.02	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.06	100.0	3.82
			Subtotal	0.06	100	3.82
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	5.0	0.19
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.1
	Lead alloy	Lead (Pb)	7439-92-1	0.06	92.5	3.53
			Subtotal	0.06	100	3.82
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.37	100.0	22
			Subtotal	0.37	100	22
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.2
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	67.16	99.87	3984.81
			Subtotal	67.25	100	3990
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.1	6.5	124.34
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.16	16.0	306.08
	Filler	Silica fused	60676-86-0	22.89	71.0	1358.23
	Flame retardant	Metal hydroxide		2.1	6.5	124.34
			Subtotal	32.25	100	1912.99
			Total	100.01	100	5933.63

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